

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM348691

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
Pacific Aerospace & Electronics, Inc.		07/20/2015	CORPORATION: WASHINGTON
RECEIVING PARTY DATA			
Name:	Johnson Bank		
Street Address:	333 East Wisconsin Avenue		
Internal Address:	Suite 82		
City:	Milwaukee		
State/Country:	WISCONSIN		
Postal Code:	53202		
Entity Type:	CORPORATION: WISCONSIN		
PROPERTY NUMBERS Total: 7			
Property Type	Number	Word Mark	
Registration Number:	1998984	HERMETIC ADVANTAGE	
Registration Number:	3488733	JUNIOR-D	
Registration Number:	3576279	LWP	
Registration Number:	3576280	LLWP	
Registration Number:	3717548	KRYOFLEX	
Registration Number:	3738316	ELECTRONIC PACKAGES FOR EXTREME ENVIRONM	
Registration Number:	3816192	PA&E	
CORRESPONDENCE DATA			
Fax Number:	4149788675		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	414 277 5675		
Email:	marta.levine@quarles.com		
Correspondent Name:	Marta S. Levine		
Address Line 1:	Quarles & Brady LLP		
Address Line 2:	411 East Wisconsin Avenue		
Address Line 4:	Milwaukee, WISCONSIN 53202		
ATTORNEY DOCKET NUMBER:	160906.00041		

CH \$190.00 1998984

NAME OF SUBMITTER:	Marta S. Levine
SIGNATURE:	/MartaLevine/
DATE SIGNED:	07/21/2015
Total Attachments: 6 source=Security Agreement IP _ Pacific Aerospace & electronoics _ Johnson Bank#page1.tif source=Security Agreement IP _ Pacific Aerospace & electronoics _ Johnson Bank#page2.tif source=Security Agreement IP _ Pacific Aerospace & electronoics _ Johnson Bank#page3.tif source=Security Agreement IP _ Pacific Aerospace & electronoics _ Johnson Bank#page4.tif source=Security Agreement IP _ Pacific Aerospace & electronoics _ Johnson Bank#page5.tif source=Security Agreement IP _ Pacific Aerospace & electronoics _ Johnson Bank#page6.tif	

**CONFIRMATORY GRANT OF SECURITY INTEREST
IN UNITED STATES PATENTS, TRADEMARKS, AND COPYRIGHTS**

THIS CONFIRMATORY GRANT OF SECURITY INTEREST IN UNITED STATES PATENTS, TRADEMARKS, AND COPYRIGHTS (the "Confirmatory Grant") is made effective as of July 20, 2015, by and from PACIFIC AEROSPACE & ELECTRONICS, INC., a Washington corporation ("Assignor"), whose principal address is 434 Olds Station Road, Wenatchee, Washington 98801, Buildings No. 7 & 8, to and in favor of JOHNSON BANK, whose principal address is 333 East Wisconsin Avenue, Suite 82, Milwaukee, Wisconsin 53202, as administrative agent ("Assignee") for the lenders (the "Lenders") from time to time parties to that certain Credit Agreement dated as of the date hereof by and among PAE Group LLC, a Delaware limited liability company, and Assignor (each a "Borrower" and, collectively, the "Borrowers"), Assignee, as administrative agent, and the Lenders, as such Credit Agreement may be amended or amended and restated or refinanced from time to time.

WHEREAS, the Borrowers (including Assignor), as debtors, and Assignee, as secured party, have entered into a Security Agreement of even date herewith (as amended or amended and restated or refinanced from time to time, the "Security Agreement") pursuant to which Assignor has granted Assignee, for the benefit of the Lenders and their affiliates, a security interest in substantially all of Assignor's personal property and assets;

WHEREAS, Assignor is the owner of the patents (the "Patents"), the trademarks and the goodwill of the business in connection therewith (the "Trademarks"), and the copyrights (the "Copyrights"), all listed on Exhibit A attached hereto, which Patents are issued or pending with the United States Patent and Trademark Office; which Trademarks are registered or pending registration with the United States Patent and Trademark Office; and which Copyrights are registered or pending with the United States Copyright Office.

WHEREAS, this Confirmatory Grant has been granted in conjunction with the security interest granted to Assignee under the Security Agreement;

NOW, THEREFORE, in consideration of the mutual covenants and agreements set forth herein and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, it is hereby agreed that:

1. Definitions. All capitalized terms not defined herein shall have the respective meaning given to them in the Security Agreement.
2. The Security Interest.

(a) This Confirmatory Grant is made to secure the satisfactory performance and payment of all the Obligations (as defined in the Credit Agreement). Upon the payment in full of all Obligations (other than contingent indemnity obligations), Assignee shall, upon such satisfaction, execute, acknowledge, and deliver to Assignor an instrument in writing releasing the security interest in the Patents, Trademarks, and Copyrights acquired under this Confirmatory Grant.

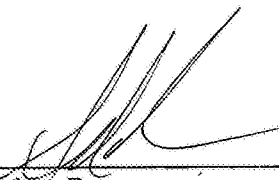
(b) Assignor hereby collaterally assigns and grants to Assignee, for the benefit of the Lenders and their affiliates, a security interest in (1) all of Assignor's right, title and interest in and to the Patents, Trademarks, and Copyrights set forth on Exhibit A, now owned or from time to time after the date hereof owned or acquired by Assignor (but excluding intent-to-use trademark applications which are described in clause (b) of the definition of Excluded Property contained in the Security Agreement), together with (2) all proceeds and products of the Patents, Trademarks, and Copyrights, and (3) all causes of action arising prior to or after the date hereof for infringement of any of the Patents, Trademarks, or Copyrights, or unfair competition regarding the same.

(c) The rights and remedies of Assignee and the Lenders and their affiliates with respect to the security interest granted herein are without prejudice to and are in addition to those set forth in the Security Agreement, all terms and provisions of which are incorporated herein by reference. In the event that any provisions of this Confirmatory Grant are deemed to conflict with the Security Agreement, the provisions of the Security Agreement shall govern.

(Signature Pages Follow)

IN WITNESS WHEREOF, Assignor has executed this Confirmatory Grant effective as of the above-indicated date.

PACIFIC AEROSPACE & ELECTRONICS,
INC.

By: 

Name: Adam Reeves

Title: Vice President and Secretary

Signature Page to Confirmatory Grant of Security Interest
in United States Patents, Trademarks and Copyrights

TRADEMARK
REEL: 005581 FRAME: 0773

CONFIRMATORY GRANT OF SECURITY INTEREST
IN UNITED STATES PATENTS, TRADEMARKS, AND COPYRIGHTS

Exhibit A - SCHEDULE OF PATENTS, TRADEMARKS, AND COPYRIGHTS

U.S. Patents

Patent Title	Pat. No. / App. No.	Issue / Filing Date
Waveguide window assembly and microwave electronics package	PN: 5986208 AN: 09/006696	Issued: Nov. 16, 1999 Filed: Jan. 14, 1998
Methods for hermetically sealing ceramic to metallic surfaces and assemblies incorporating such seals	PN: 6221513 AN: 09/076230	Issued: Apr. 24, 2001 Filed: May 12, 1998
Methods for treating ceramic materials and improved treated ceramic materials produced thereby	PN: 6232004 AN: 09/235223	Issued: May 15, 2001 Filed: Jan. 22, 1999
Composite materials and methods for manufacturing composite materials	PN: 6284389 AN: 09/303196	Issued: Sep. 4, 2001 Filed: Apr. 30, 1999
Electronics packages having a composite structure and methods for manufacturing such electronics packages	PN: 6355362 AN: 09/302590	Issued: Mar. 12, 2002 Filed: Apr. 30, 1999
RF connectors having ground springs	PN: 7131867 AN: 11/123370	Issued: Nov. 7, 2006 Filed: May 6, 2005
Firearms and firearm components comprising bonded multi-metallic materials	PN: 8136286 AN: 12/823383	Issued: Mar. 20, 2012 Filed: Jun. 25, 2010
Connector assemblies incorporating ceramic inserts having conductive pathways and interfaces	PN: 8189333 AN: 12/559210	Issued: May 29, 2012 Filed: Sep. 14, 2009
Firearms and firearm components comprising bonded multi-metallic materials; methods of manufacture	PN: 8522471 AN: 13/178423	Issued: Sep. 3, 2013 Filed: Jul. 7, 2011
Methods of manufacturing firearms and firearms components comprising bonded multi-metallic materials	PN: 8904695 AN: 14/014279	Issued: Dec. 9, 2014 Filed: Aug. 29, 2013

U.S. Trademarks

U.S. Trademark	Reg. No. / Ser. No.	Reg. / Filing Date	Goods / Services
HERMETIC ADVANTAGE	RN: 1998984 SN: 74521789	Registered: Sep. 10, 1996 Filed: May 3, 1994 Last Renewal: Sep. 10, 2006	(Int'l Class: 09) electronic components, namely electronic connectors and hermetic sealing devices

U.S. Trademark	Reg. No. / Ser. No.	Reg. / Filing Date	Goods / Services
JUNIOR-D	RN: 3488733 SN: 78957018	Registered: Aug. 19, 2008 Filed: Aug. 21, 2006	(Int'l Class: 09) electronic connectors in the nature of hermetic sealing devices, namely, dc connectors having controlled coefficient of thermal expansion characteristics, unique chemical bonding properties, and comprising polycrystalline ceramic substances
LWP	RN: 3576279 SN: 78957032	Registered: Feb. 17, 2009 Filed: Aug. 21, 2006 Affidavit(s): 8 & 15, July 12, 2014	(Int'l Class: 09) electronic components, namely, electronic connectors and hermetic sealing devices, namely, rf connectors
LLWP	RN: 3576280 SN: 78957039	Registered: Feb. 17, 2009 Serial No.: 78-957039 Filed: Aug. 21, 2006 Affidavit(s): 8 & 15, July 12, 2014	(Int'l Class: 09) electronic components, namely, electronic connectors and hermetic sealing devices, namely, rf connectors
KRYOFLEX	RN: 3717548 SN: 77589387	Registered: Dec. 1, 2009 Serial No.: 77-589387 Filed: Oct. 9, 2008	(Int'l Class: 01) ceramic materials in the nature of powders for use in the manufacture of electronic components and devices, namely, hermetic connectors, integrated electronic packaging, electromagnetic interference filters, for use in defense, space, medical, aviation, energy, nuclear, marine, fiber optics, and communication industries
ELECTRONIC PACKAGES FOR EXTREME ENVIRONMENTS	RN: 3738316 SN: 77244923	Registered: Jan. 12, 2010 Filed: Aug. 1, 2007 Register Type: Supplemental Register	(Int'l Class: 40) manufacture to the order and specification of others in the field of electronic components and devices, namely, integrated electronic packaging, hermetic connectors, non-hermetic connectors, rf connectors, microwave connectors, dc connectors, high pressure connectors, fiber optic connectors, hermetic windows, machined housings, electromagnetic interference filters, explosively bonded metals

U.S. Trademark	Reg. No. / Ser. No.	Reg. / Filing Date	Goods / Services
PA&E	RN: 3816192 SN: 77589448	Registered: Jul. 13, 2010 Filed: Oct. 9, 2008	(Int'l Class: 09) electronic components and devices, namely, hermetic electronic connectors, integrated hermetic electronic packaging in the nature of protective features built into the electronic product, and electromagnetic interference filters for use in defense, space, medical, aviation, energy, nuclear, marine, fiber optics, and communication industries (Int'l Class: 40) manufacturing of electronic components and devices to the order and specifications of others